

	<h1>Tentative</h1>	DMC364A2	
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DMC364A2

Silicon NPN epitaxial planar type (Tr1)

Silicon NPN epitaxial planar type (Tr2)

For digital circuit

Marking Symbol : G3

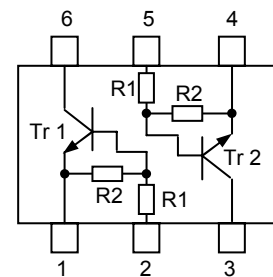
Package Code : SSSMini6-F2-B

Absolute Maximum Ratings $T_a = 25\text{ }^\circ\text{C}$

Parameter		Symbol	Rating	Unit
Tr1	Collector-base voltage (Emitter open)	VCBO	50	V
	Collector-emitter voltage (Base open)	VCEO	50	V
Tr2	Collector current	IC	80	mA
Overall	Total power dissipation *1	PT	125	mW
	Junction temperature	Tj	150	$^\circ\text{C}$
	Storage temperature	Tstg	-55 to +150	$^\circ\text{C}$

Note: 1. *1 Measuring on substrate at 17 mm × 10 mm × 1 mm

Internal Connection



Resistance value	R1	22	k Ω
	R2	22	k Ω

Pin name

1.	Emitter(Tr1)	4.	Emitter(Tr2)
2.	Base(Tr1)	5.	Base(Tr2)
3.	Collector(Tr2)	6.	Collector(Tr1)

Electrical Characteristics $T_a = 25\text{ }^\circ\text{C} \pm 3\text{ }^\circ\text{C}$

Tr1,Tr2

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	VCBO	IC = 10 μA , IE = 0	50			V
Collector-emitter voltage (Base open) *1	VCEO	IC = 2 mA, IB = 0	50			V
Collector-base cutoff current (Emitter open)	ICBO	VCB = 50 V, IE = 0			0.1	μA
Collector-emitter cutoff current (Base open)	ICEO	VCE = 50 V, IB = 0			0.5	μA
Emitter-base cutoff current (Collector open)	IEBO	VEB = 6 V, IC = 0			0.2	mA
Forward current transfer ratio	hFE	VCE = 10 V, IC = 5 mA	60			-
Collector-emitter saturation voltage	VCE(sat)	IC = 10 mA, IB = 0.5 mA			0.25	V
Input voltage	Vi(on)	VCE = 0.2 V, IC = 5 mA	2.6			V
	Vi(off)	VCE = 5 V, IC = 100 μA			0.8	
Input resistance	R1		-30%	22	+30%	k Ω
Resistance ratio	R1/R2		0.8	1.0	1.2	-

Note: 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

2. *1 Pulse measurement

Packing

Embossed type (Thermo-compression sealing) R specification : 10 000 pcs / reel

2010.3.11	2010.9.27	
Prepared	Revised	

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